

# AuLTRA™-fine Die-Attach AuSn Ribbon

AuLTRA™-fine die-attach AuSn ribbon is designed for high-volume, fully automated laser diode assembly. AuLTRA™-fine die-attach AuSn ribbon features:

- No warping, bends, or breaks
- Continuous lengths for auto-feed systems



Contact us to learn more about our AuSn preforms, Quick Turn Program, and our wide variety of gold-based solders for high reliability.

Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com](http://www.indium.com)

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.*

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# Indium Corporation

Indium Corporation is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets.

We develop, manufacture, and market solders; electronics assembly and packaging materials; thermal interface materials; pure indium, gallium, germanium, and tin; as well as alloys and inorganic compounds. We offer a closed-loop reclaim system for these metals.

Indium Corporation's scientists, application engineers, and technical support engineers work closely with our customers to develop custom solutions to their technical problems and optimize their processes to:

- Increase yields
- Reduce defects
- Increase revenues
- Deliver high value
- Improve customer satisfaction and return on investment

## From One Engineer To Another®

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